



eUICC SIM Datasheet

V1.1 | JULY 2020

Triple-cut form factor

2FF, 3FF, 4FF

Product Overview

A secure IoT SIM card for a global cell network built for M2M data with easy activation, transparent pricing, and developer-friendly tools.

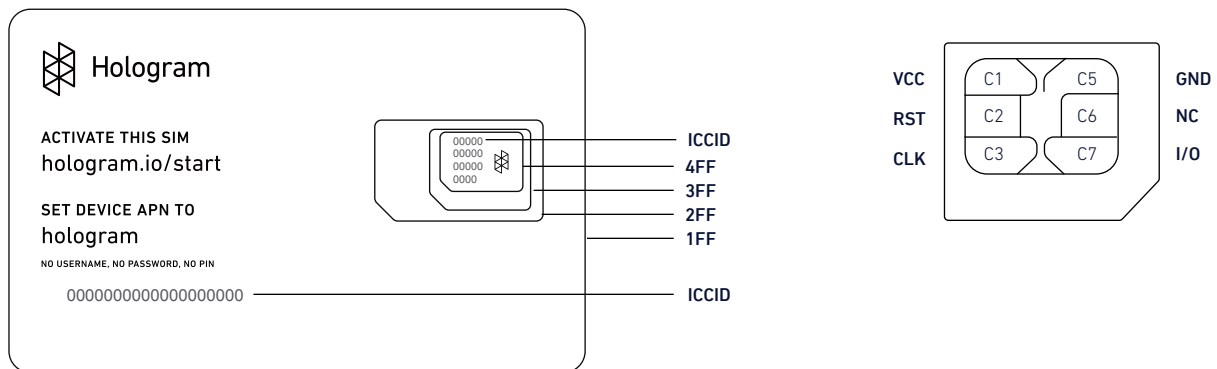
Orderable part numbers

| | |
|-------------------|-------------------|
| SIM-E-TRI-GL | SIM-E-TRI-LS |
| SIM-E-TRI-GL-10 | SIM-E-TRI-LS-10 |
| SIM-E-TRI-GL-100 | SIM-E-TRI-LS-100 |
| SIM-E-TRI-GL-1000 | SIM-E-TRI-LS-1000 |

Network Availability

Works globally with Hologram's 2G through LTE network where coverage is available.
 More information: <https://www.hologram.io/pricing/coverage>

Mechanical specifications



Size

| | | |
|-----|-----------|------------------------|
| 1FF | Full-size | 85.5 x 53.98 x 0.76 mm |
| 2FF | Mini-SIM | 25 x 15 x 0.76 mm |
| 3FF | Micro-SIM | 15 x 12 x 0.76 mm |
| 4FF | Mini-SIM | 12.3 x 8.8 x 0.76 mm |

Pin Definitions

| | | |
|----|-----|---------------|
| C1 | VCC | Input Voltage |
| C2 | RST | Reset |
| C3 | CLK | Clock |
| C5 | GND | Ground |
| C6 | NC | No Connect |
| C7 | I/O | Input/Output |

Hardware Specifications

| Environmental | Standard Grade | Industrial Grade |
|---------------|------------------------|------------------------|
| Temperature | -25–85°C | -40–105°C |
| Lifespan | 25 years @ 25°C | 15 years @ 85°C |
| Lifespan | 100K read/write cycles | 500K read/write cycles |

| Electrical | Standard Grade | Industrial Grade |
|-------------------|----------------|------------------|
| Operating Voltage | 1.62V–5.5V | 1.62V–5.5V |

AC electrical parameters standards

ETSI 3GPP TS 102 221(UICC Terminal Interface Physical & Logical Characteristics)

ETSI TS 102 671 v9.1.0(M2M Physical and Logical Characteristics)

ISO 7816-3 standard for (Cards with Contacts - Electrical interface and transmission protocols)

Compliance

| | | |
|-------------------------|--|--|
| Chip |  Common Criteria | EAL: PP-0084/35 |
| OS |  GSMA | SGP.11 RSP v3.1; SGP.14 eUICC PKI v1.1; SGP.02 v3.2 ; SGP.05 eUICC PP-0089 |
| |  simalliance | eUICC Profile Package v2.1 |
| |  GLOBALPLATFORM® | Product Qualification |
| Production |  GSMA Security Accreditation Scheme | SAS-UP eUICC : EUM |
| Remote SIM provisioning |  GSMA | SGP.01 RSP v1.1 ; SGP.11 RSP v3.1 & 3.2; SGP.14 eUICC PKI v1.1 ; SAS-SM |

RoHS and REACH Compliance

Hologram, Inc. hereby declares that the aforementioned Hologram products, placed on the European Community market by the Company and its subsidiaries is compliant with Directive 2011/65/EU on the Restriction of Certain Hazardous Substances in Electrical and Electronic Equipment.

More information: <https://www.samsung.com/semiconductor/about-us/global-compliance/>

Embedded form factor

MFF2, QFN8

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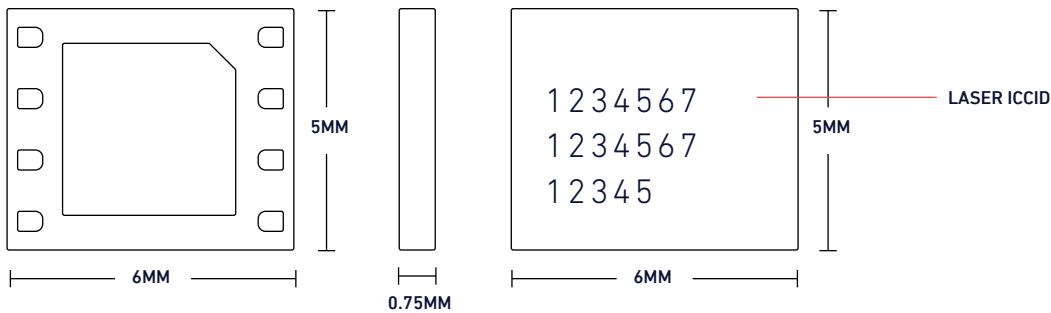
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| SIM-E-MFF2-GL-100 | SIM-E-MFF2-LS-100 |
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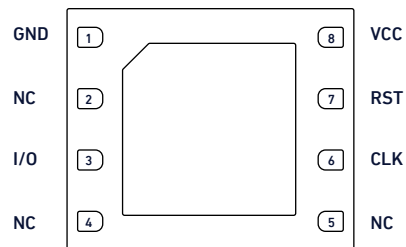
Bottom View



Pin Definitions

| | | |
|---|-----|---------------|
| 1 | GND | Ground |
| 2 | NC | No Connect |
| 3 | I/O | Input/Output |
| 4 | NC | No Connect |
| 5 | NC | No Connect |
| 6 | CLK | Clock |
| 7 | RST | Reset |
| 8 | VCC | Input Voltage |

Top View



Size

6 x 5 x 0.75mm

Hardware Specifications

| Environmental | Standard Grade | Industrial Grade |
|---------------|------------------------|------------------------|
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| Lifespan | 25 years @ 25°C | 15 years @ 85°C |
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